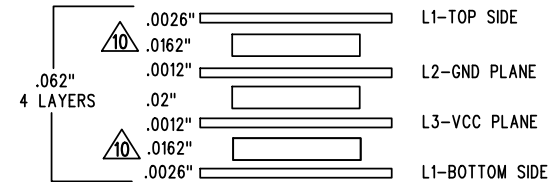


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	PRODUCTION	JOHN C.	12-12-16

LAYER STRUCTURE for FR-370HR, DIELECTRIC CONSTANT=4.7

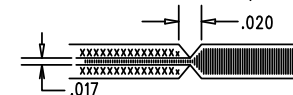


NOTES: UNLESS OTHERWISE SPECIFIED

- FAB PER IPC-A-600.
- MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, ISOLA FR-370HR OR EQUIVALENT.
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 4 LAYERS WITH 2 OZ. CU ON THE OUTER LAYERS AND 1 OZ. CU ON THE INNER LAYERS.
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
0.00" ARE PRIMARY DATUMS.
- DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
-HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER
- FINISH: -SMOBC USING LPI BOTH SIDES, COLOR GREEN.
-GOLD IMMERSION BOTH SIDES.
-FOR SILKSCREENS: USE WHITE NON-CONDUCTIVE INK.

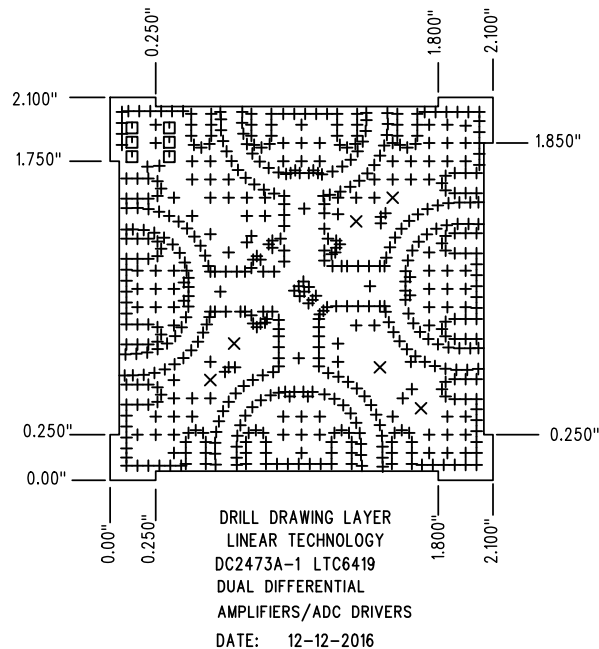
6. CONTROLLED 50 OHM +/-5% IMPEDANCE FOR LAYERS 1-2 USING 0.030" TRACE

- DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE. PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
- PCBS ARE TO BE RoHS COMPLIANT.
- SCORING FOR PANELIZED PCB (PRODUCTION FAB ONLY):



10. SUBJECT TO CHANGE BY MANUFACTURER, DEPENDING ON DIELECTRIC CONSTANT DEVIATIONS. PLEASE CONSULT LTC.

11. INNER AND OUTER LAYER COPPER SHALL BE EXPOSED ALONG BOARD EDGES. DO NOT MODIFY INNER LAYER COPPER BACKOFF OUTLINE (SMA CONNECTOR).



SIZE	QTY	SYM	PLATED	TOL
0.006	593	+	YES	+/-0.003
0.066	6	X	YES	+/-0.003
0.031	6	□	YES	+/-0.003

UNLESS OTHERWISE SPECIFIED		APPROVALS			
DIMENSIONS ARE IN INCHES		PCB DES.	AK		
TOLERANCES:		APP ENG.	JOHN C.	TITLE: FABRICATION DRAWING	
0.XX" = ±0.01"				DUAL DIFFERENTIAL	
0.XXX" = ±0.005"				AMPLIFIERS/ADC DRIVERS	
INTERPRET DIM AND TOL PER ASME Y14.5M-1994				SIZE	IC NO. LTC6419
THIRD ANGLE PROJECTION				N/A	DEMO BOARDS 2473A
		SCALE = NONE		FILENAME: DC2473A-1.PCB	REV 1
				SHT 1 OF 1	

1630 MCCARTHY BLVD
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